



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-08-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	T8BV*L082CA6	A	BO2A	2017-08-23
Amount	UoM	Unit type	ST ECOPACK Grade	
5300	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SIP	10.3 x 19.6 x 4.5	8	Through-hole
Comment	Package: BV MULTIWATT 8L ON LINE; MDF valid for TDA7264		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T8BV*L082CA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other Inorganic materials	7.993	mg	supplier	die	Silicon (Si)	7440-21-3		7.737	mg	967972	1460
				supplier	metallization	Aluminium (Al)	7429-90-5		0.098	mg	12261	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.034	mg	4254	6
				supplier	Passivation	Silicon Oxide	7631-86-9		0.048	mg	6005	9
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.006	mg	751	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.016	mg	2002	3
Leadframe	Copper & its alloys	4287.580	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.054	mg	6756	10
				supplier	alloy	Copper (Cu)	7440-50-8		4279.372	mg	998086	807429
				supplier	alloy	Iron (Fe)	7439-89-6		1.971	mg	460	372
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		3.599	mg	839	679
				supplier	metallization	Silver (Ag)	7440-22-4		2.638	mg	615	498
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.640	mg	975037	1253
Soft solder	Solder	6.810	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.102	mg	14978	19
				supplier	solder	Tin (Sn)	7440-31-5		0.068	mg	9985	13
				supplier	wire	Copper (Cu)	7440-50-8		3.420	mg	1000000	645
Encapsulation	Other Organic Materials	987.766	mg	supplier	mold compound	Silica vitreous	60676-86-0		770.457	mg	780000	145369
				supplier	mold compound	Bisphenol F type epoxy resin	9003-36-5		93.838	mg	95000	17705
				supplier	mold compound	Phenol resin	9003-35-4		82.972	mg	84000	15655
				supplier	mold compound	Antimony Trioxide	1309-64-4		16.792	mg	17000	3168
				supplier	mold compound	Brominated flame retardant	Proprietary		14.817	mg	15001	2796
				supplier	mold compound	Silica Cristobalite	14464-46-1		4.939	mg	5000	932
connections coating	Solder	6.431	mg	supplier	mold compound	Carbon Black	1333-86-4		3.951	mg	4000	745
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.431	mg	1000000	1213